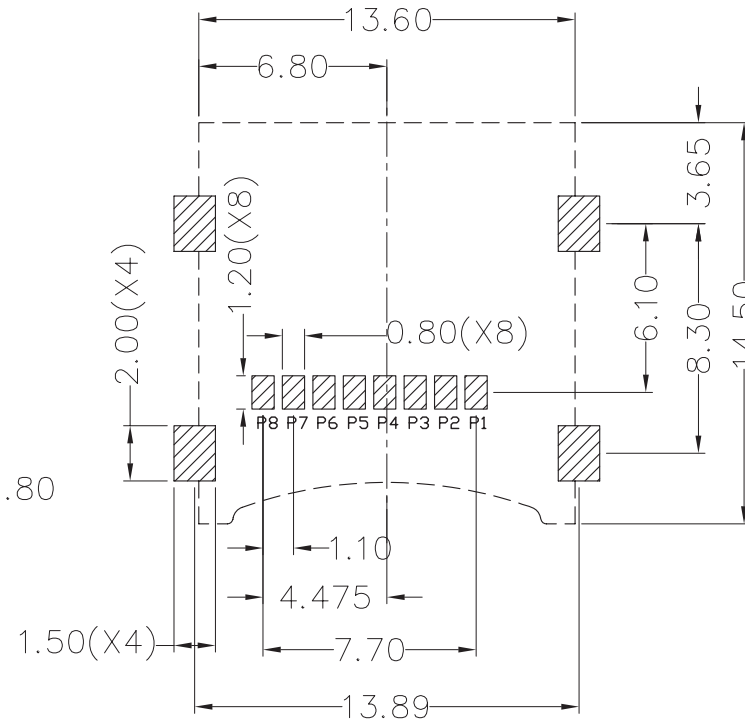
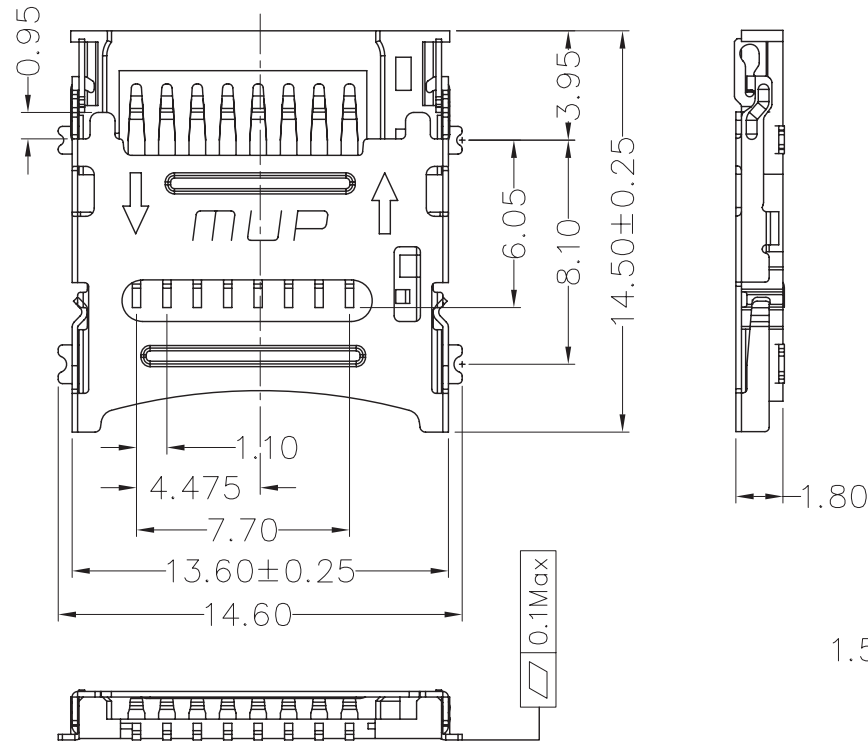


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



MicroSD CARD	
Pin No.	NAME
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1

RECOMMENDED P.C.B LAYOUT COMPONENT SIDE(TOLERANCE ±0.05)

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions:14.50LX13.60WX1.80H mm

Weight:Approx0.70g

Durability:5000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vaporphase:215°C,30sec.Max

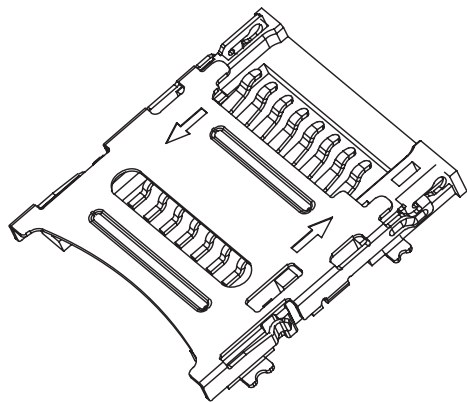
IR reflow:250°C,5sec.Max

Manual soldering:370°C,3sec.Max

4.Environmental Characteristics

Operating temperature:-40°C~+85°C

Operating humidity:10%~+95%RH



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	
Unless otherwise specified, other tolerance are:			 CONNECT MALL Tel. 1599-6005	
X	±0.35	X'	±5'	NAME: Memory Card
X.X	±0.25	X.X'	±4'	MODEL NO: MSDC-M61608
X.XX	±0.15	X.XX'	±3'	TYPE: H1.80 mm
X.XXX	±0.10	X.XXX'	±2'	
PROJ.	UNIT	SCALE	DRAWN: Zoey Jul.08.2009	
⊕	mm	1:1	CHECKED: Jimmy Jul.08.2009	
CUSTOMER DRAWING			APPROVAL: Simon Jul.08.2009	
			DWG NO.: DWG-MSDC-M61608-002	
			SHEET 1/1	REVISION X1